

## 1. General description

Planar passivated high commutation three quadrant triac in a SOT78 (TO-220AB) plastic package intended for use in circuits where high static and dynamic dV/dt and high di/dt can occur. This "series CT" triac will commutate the full RMS current at the maximum rated junction temperature ( $T_j = 150^\circ\text{C}$ ) without the aid of a snubber where "high junction operating temperature capability" is required.

## 2. Features and benefits

- 3Q technology for improved noise immunity
- High commutation capability with maximum false trigger immunity
- High immunity to false turn-on by dV/dt
- High junction operating temperature capability
- High voltage capability
- Planar passivated for voltage ruggedness and reliability
- Triggering in three quadrants only

## 3. Applications

- Applications subject to high temperature
- Electronic thermostats (heating and cooling)
- Motor controls for home appliances
- Rectifier-fed DC inductive loads e.g. DC motors and solenoids

## 4. Quick reference data

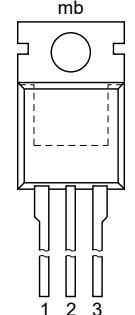
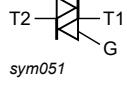
Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$V_{DRM}$	repetitive peak off-state voltage			-	-	800	V
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{mb} \leq 134^\circ\text{C}$ ; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>		-	-	6	A
$I_{TSM}$	non-repetitive peak on-state current	full sine wave; $T_{j(\text{init})} = 25^\circ\text{C}$ ; $t_p = 20\text{ ms}$ ; <a href="#">Fig. 4</a> ; <a href="#">Fig. 5</a>		-	-	60	A
		full sine wave; $T_{j(\text{init})} = 25^\circ\text{C}$ ; $t_p = 16.7\text{ ms}$		-	-	66	A
$T_j$	junction temperature			-	-	150	$^\circ\text{C}$
<b>Static characteristics</b>							
$I_{GT}$	gate trigger current	$V_D = 12\text{ V}$ ; $I_T = 0.1\text{ A}$ ; T2+ G+; $T_j = 25^\circ\text{C}$ ; <a href="#">Fig. 7</a>		4	-	35	mA

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
		$V_D = 12 \text{ V}$ ; $I_T = 0.1 \text{ A}$ ; T2+ G-; $T_j = 25^\circ\text{C}$ ; <a href="#">Fig. 7</a>		4	-	35	mA
		$V_D = 12 \text{ V}$ ; $I_T = 0.1 \text{ A}$ ; T2- G-; $T_j = 25^\circ\text{C}$ ; <a href="#">Fig. 7</a>		4	-	35	mA
$I_H$	holding current	$V_D = 12 \text{ V}$ ; $T_j = 25^\circ\text{C}$ ; <a href="#">Fig. 9</a>		-	-	35	mA
$V_T$	on-state voltage	$I_T = 7 \text{ A}$ ; $T_j = 25^\circ\text{C}$ ; <a href="#">Fig. 10</a>		-	1.3	1.6	V
<b>Dynamic characteristics</b>							
$dV_D/dt$	rate of rise of off-state voltage	$V_{DM} = 536 \text{ V}$ ; $T_j = 150^\circ\text{C}$ ; ( $V_{DM} = 67\%$ of $V_{DRM}$ ); exponential waveform; gate open circuit		500	-	-	V/ $\mu$ s
$dI_{com}/dt$	rate of change of commutating current	$V_D = 400 \text{ V}$ ; $T_j = 150^\circ\text{C}$ ; $I_{T(RMS)} = 6 \text{ A}$ ; $dV_{com}/dt = 20 \text{ V}/\mu\text{s}$ ; (snubberless condition); gate open circuit		10	-	-	A/ms
		$V_D = 400 \text{ V}$ ; $T_j = 150^\circ\text{C}$ ; $I_{T(RMS)} = 6 \text{ A}$ ; $dV_{com}/dt = 10 \text{ V}/\mu\text{s}$ ; gate open circuit		12	-	-	A/ms
		$V_D = 400 \text{ V}$ ; $T_j = 150^\circ\text{C}$ ; $I_{T(RMS)} = 6 \text{ A}$ ; $dV_{com}/dt = 1 \text{ V}/\mu\text{s}$ ; gate open circuit		20	-	-	A/ms

## 5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	T1	main terminal 1		
2	T2	main terminal 2		
3	G	gate		
mb	T2	mounting base; main terminal 2	 <b>TO-220AB (SOT78)</b>	 sym051

## 6. Ordering information

Table 3. Ordering information

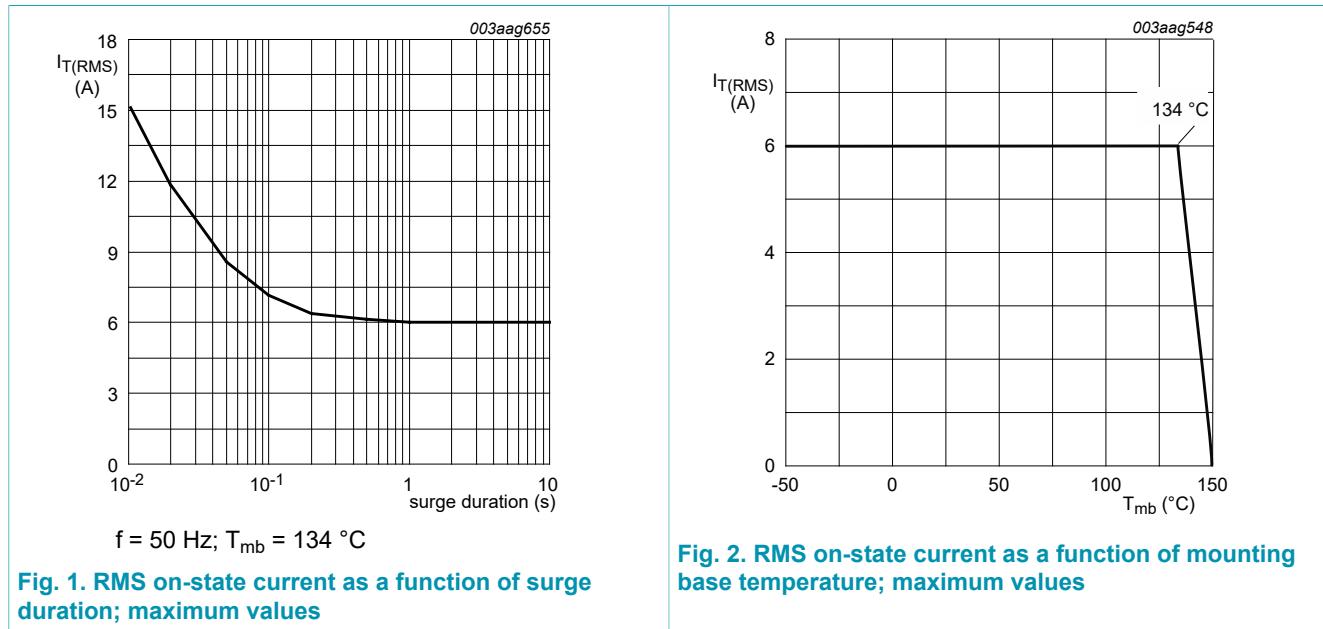
Type number	Package			Version
	Name	Description		
BTA206-800CT	TO-220AB	plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB		SOT78

## 7. Limiting values

**Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
$V_{DRM}$	repetitive peak off-state voltage			-	800	V
$I_{T(RMS)}$	RMS on-state current	full sine wave; $T_{mb} \leq 134^{\circ}\text{C}$ ; <a href="#">Fig. 1</a> ; <a href="#">Fig. 2</a> ; <a href="#">Fig. 3</a>		-	6	A
$I_{TSM}$	non-repetitive peak on-state current	full sine wave; $T_{j(\text{init})} = 25^{\circ}\text{C}$ ; $t_p = 20\text{ ms}$ ; <a href="#">Fig. 4</a> ; <a href="#">Fig. 5</a>		-	60	A
		full sine wave; $T_{j(\text{init})} = 25^{\circ}\text{C}$ ; $t_p = 16.7\text{ ms}$		-	66	A
$I^2t$	$I^2t$ for fusing	$t_p = 10\text{ ms}$ ; SIN		-	18	$\text{A}^2\text{s}$
$dI_T/dt$	rate of rise of on-state current	$I_G = 0.2\text{ A}$		-	100	$\text{A}/\mu\text{s}$
$I_{GM}$	peak gate current			-	2	A
$P_{GM}$	peak gate power			-	5	W
$P_{G(AV)}$	average gate power	over any 20 ms period		-	0.5	W
$T_{stg}$	storage temperature			-40	150	$^{\circ}\text{C}$
$T_j$	junction temperature			-	150	$^{\circ}\text{C}$



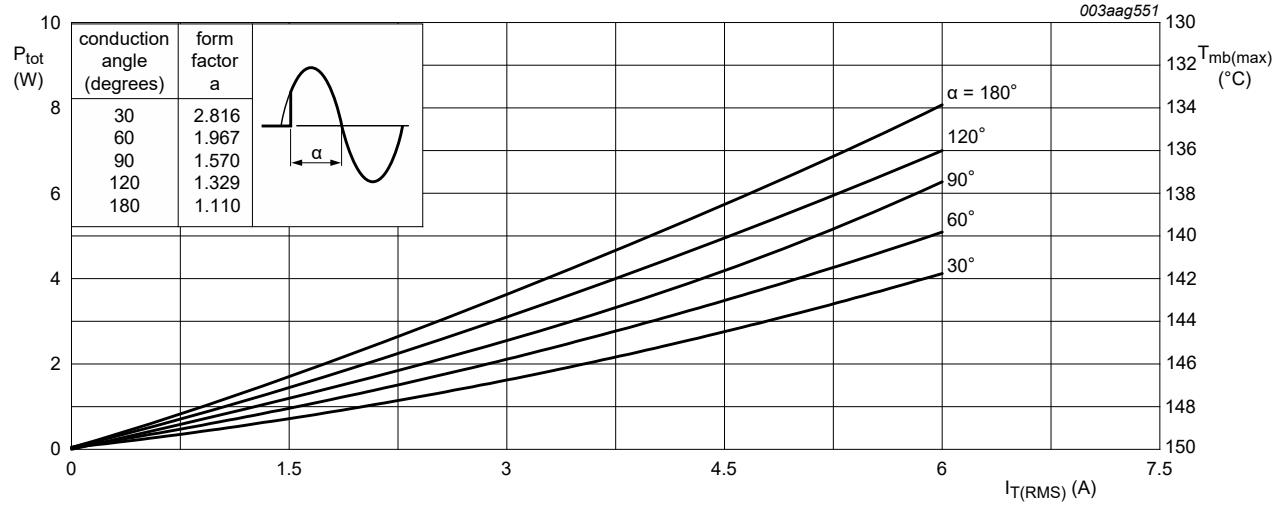


Fig. 3. Total power dissipation as a function of RMS on-state current; maximum values

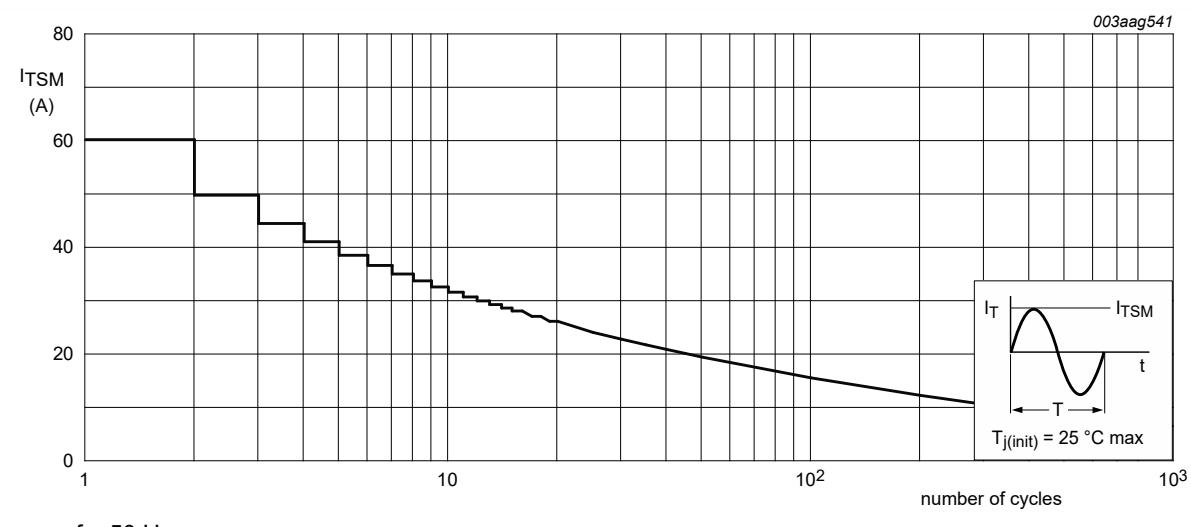
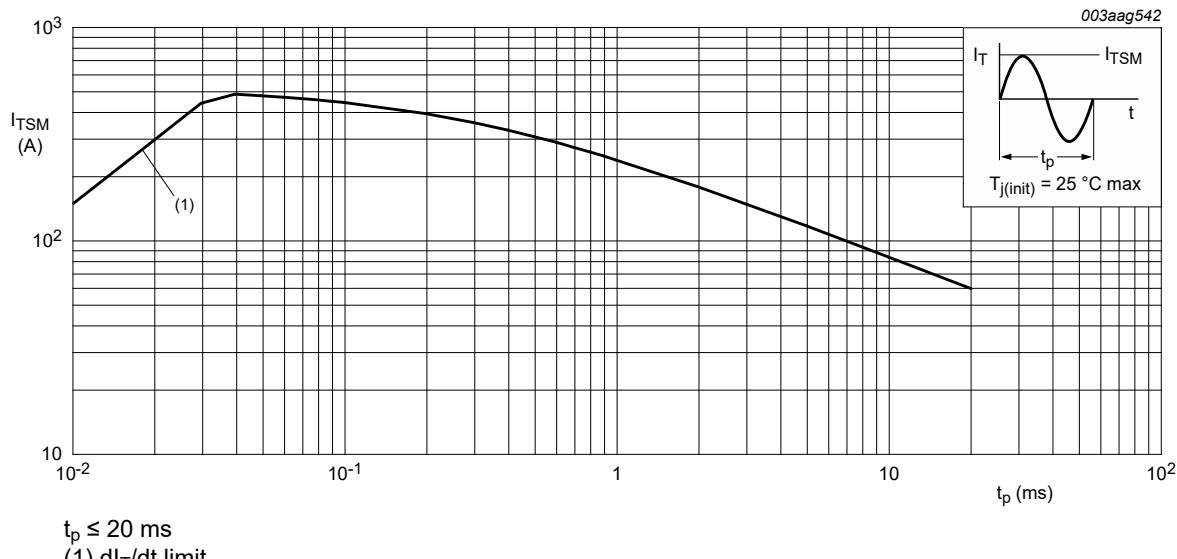


Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values



**Fig. 5. Non-repetitive peak on-state current as a function of pulse width; maximum values**

## 8. Thermal characteristics

Table 5. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	full cycle; Fig. 6	-	-	2	K/W
		half cycle; Fig. 6	-	-	2.4	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air	-	60	-	K/W

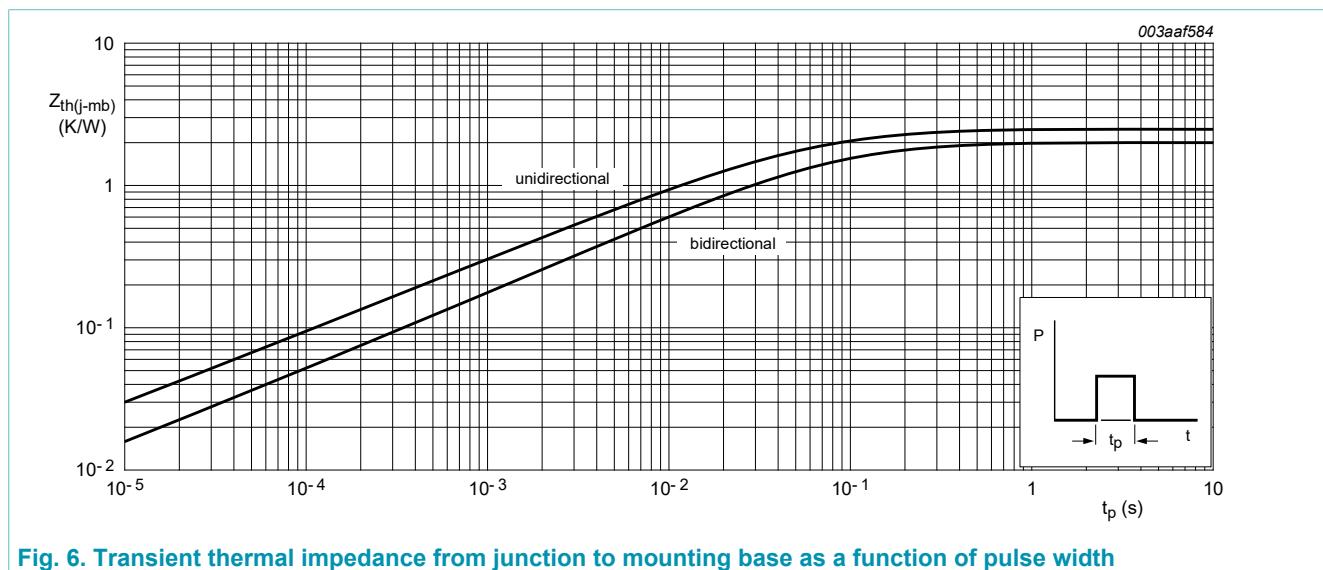


Fig. 6. Transient thermal impedance from junction to mounting base as a function of pulse width

## 9. Characteristics

**Table 6. Characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Static characteristics</b>						
I <sub>GT</sub>	gate trigger current	V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2+ G+; T <sub>j</sub> = 25 °C; <a href="#">Fig. 7</a>	4	-	35	mA
		V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2+ G-; T <sub>j</sub> = 25 °C; <a href="#">Fig. 7</a>	4	-	35	mA
		V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T2- G-; T <sub>j</sub> = 25 °C; <a href="#">Fig. 7</a>	4	-	35	mA
I <sub>L</sub>	latching current	V <sub>D</sub> = 12 V; I <sub>G</sub> = 0.1 A; T2+ G+; T <sub>j</sub> = 25 °C; <a href="#">Fig. 8</a>	-	-	50	mA
		V <sub>D</sub> = 12 V; I <sub>G</sub> = 0.1 A; T2+ G-; T <sub>j</sub> = 25 °C; <a href="#">Fig. 8</a>	-	-	60	mA
		V <sub>D</sub> = 12 V; I <sub>G</sub> = 0.1 A; T2- G-; T <sub>j</sub> = 25 °C; <a href="#">Fig. 8</a>	-	-	50	mA
I <sub>H</sub>	holding current	V <sub>D</sub> = 12 V; T <sub>j</sub> = 25 °C; <a href="#">Fig. 9</a>	-	-	35	mA
V <sub>T</sub>	on-state voltage	I <sub>T</sub> = 7 A; T <sub>j</sub> = 25 °C; <a href="#">Fig. 10</a>	-	1.3	1.6	V
V <sub>GT</sub>	gate trigger voltage	V <sub>D</sub> = 12 V; I <sub>T</sub> = 0.1 A; T <sub>j</sub> = 25 °C; <a href="#">Fig. 11</a>	-	0.8	1	V
		V <sub>D</sub> = 400 V; I <sub>T</sub> = 0.1 A; T <sub>j</sub> = 150 °C	0.25	-	-	V
I <sub>D</sub>	off-state current	V <sub>D</sub> = 800 V; T <sub>j</sub> = 150 °C	-	0.4	2	mA
<b>Dynamic characteristics</b>						
dV <sub>D</sub> /dt	rate of rise of off-state voltage	V <sub>DM</sub> = 536 V; T <sub>j</sub> = 150 °C; (V <sub>DM</sub> = 67% of V <sub>DRM</sub> ); exponential waveform; gate open circuit	500	-	-	V/μs
dI <sub>com</sub> /dt	rate of change of commutating current	V <sub>D</sub> = 400 V; T <sub>j</sub> = 150 °C; I <sub>T(RMS)</sub> = 6 A; dV <sub>com</sub> /dt = 20 V/μs; (snubberless condition); gate open circuit	10	-	-	A/ms
		V <sub>D</sub> = 400 V; T <sub>j</sub> = 150 °C; I <sub>T(RMS)</sub> = 6 A; dV <sub>com</sub> /dt = 10 V/μs; gate open circuit	12	-	-	A/ms
		V <sub>D</sub> = 400 V; T <sub>j</sub> = 150 °C; I <sub>T(RMS)</sub> = 6 A; dV <sub>com</sub> /dt = 1 V/μs; gate open circuit	20	-	-	A/ms

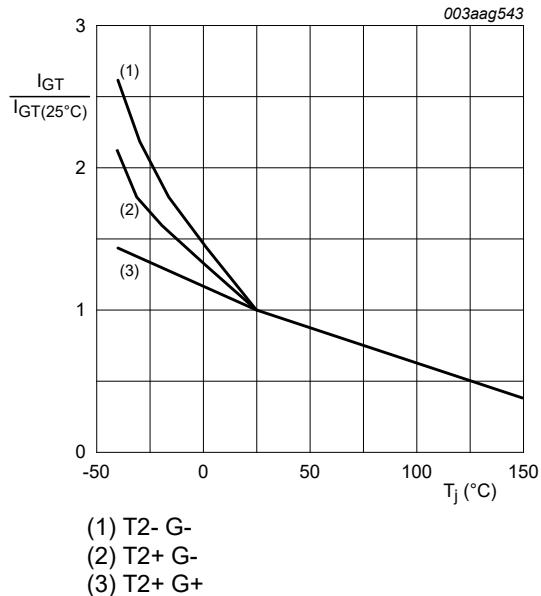


Fig. 7. Normalized gate trigger current as a function of junction temperature

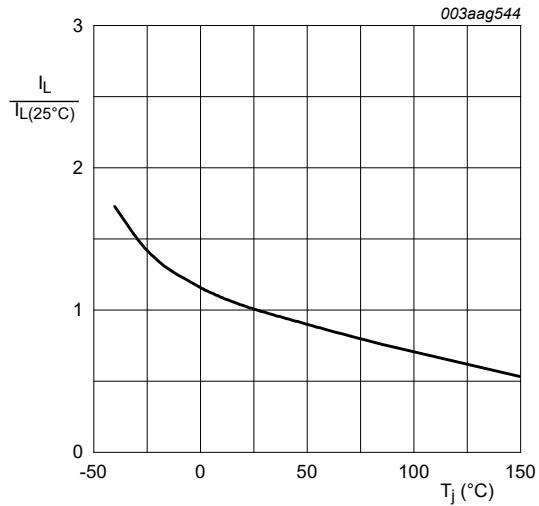


Fig. 8. Normalized latching current as a function of junction temperature

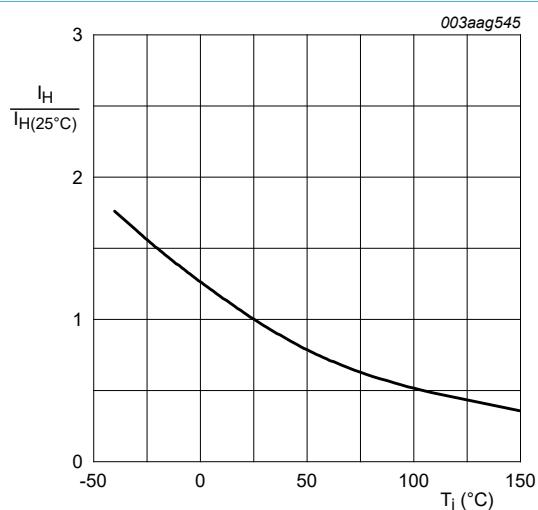


Fig. 9. Normalized holding current as a function of junction temperature

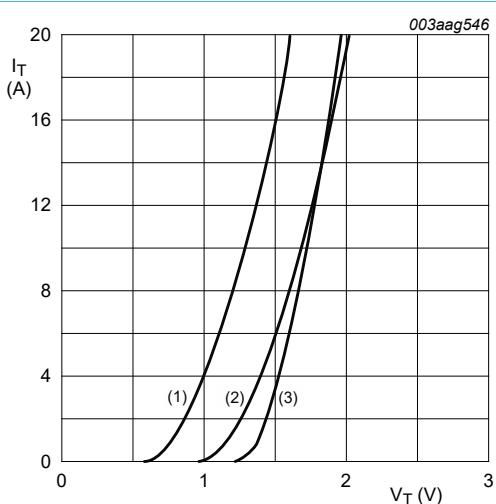
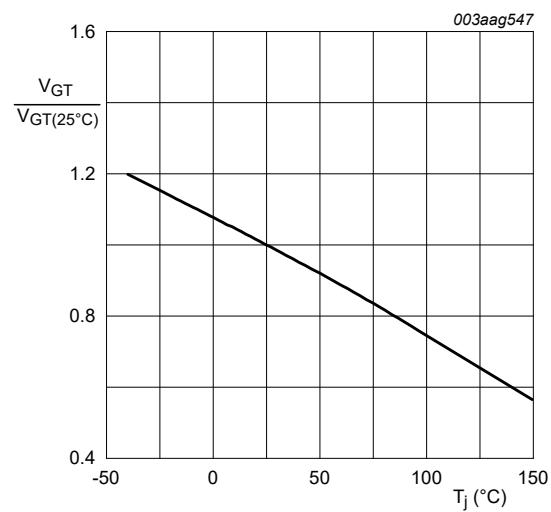


Fig. 10. On-state current as a function of on-state voltage

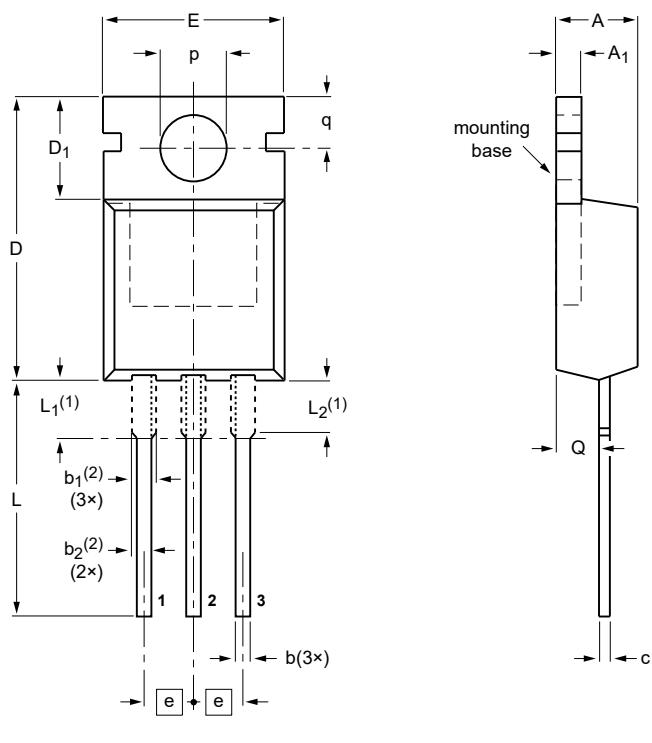


**Fig. 11. Normalized gate trigger voltage as a function of junction temperature**

## 10. Package outline

Plastic single-ended package; heatsink mounted; 1 mounting hole; 3-lead TO-220AB

SOT78



0 5 10 mm  
scale

DIMENSIONS (mm are the original dimensions)

UNIT	A	A <sub>1</sub>	b	b <sub>1(2)</sub>	b <sub>2(2)</sub>	c	D	D <sub>1</sub>	E	e	L	L <sub>1(1)</sub>	L <sub>2(1)</sub> max.	p	q	Q
mm	4.7	1.40	0.9	1.6	1.3	0.7	16.0	6.6	10.3	2.54	15.0	3.30	3.0	3.8	3.0	2.6
	4.1	1.25	0.6	1.0	1.0	0.4	15.2	5.9	9.7		12.8	2.79	3.0	3.5	2.7	2.2

### Notes

1. Lead shoulder designs may vary.
2. Dimension includes excess dambar.

### IMPORTANT NOTICE – PLEASE READ CAREFULLY

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